

A new foundation for electronics.

Lignin-based resin systems, prepregs
and laminate cores for printed circuit boards.

COMPANY AND MATERIAL PROGRAMME

Lignin-based PCB materials / October 2026

One platform. Three material formats.

Lignity brings resin and reinforcement development into one material programme. The initial focus is the insulating layers of printed circuit boards.

01 / Resin systems

Lignin-based thermoset chemistry for reinforced PCB substrates. The material approach connects formulation, curing and composite behaviour.

02 / Prepregs

A partially cured, B-stage composite format combining resin and bio-based reinforcement. Handling, resin flow and lamination connect chemistry with PCB manufacturing.

03 / Laminate cores

Fully cured, C-stage structural material formats. The evaluation priorities include stability, adhesion, electrical behaviour and thermal response.

Resin chemistry, reinforcement and curing connect these formats within one PCB material platform.

Material engineering. Industrial purpose.

Lignity connects material architecture, characterisation and manufacturing collaboration around the requirements of printed circuit boards.

01 / Define the application

Agree requirements, an appropriate reference material and the questions that will guide evaluation.

02 / Engineer and characterise

Connect chemistry, reinforcement and curing through defined samples, test methods and conditions.

03 / Evaluate with manufacturing partners

Use the evidence to shape processing trials, demonstration boards and the next qualification step.

Build the next step with us.

Industrial / research / feedstock / investment

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